12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20250519001.1
Qualification of additional Assembly sites for select QFN devices
Change Notification / Sample Request

Date: May 20, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250519001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CDCLVP2102RGTT	CDCLVP2102RGTT
TUSB2551ARGTR	595-TUSB2551ARGTR
TPS62261DRVR	TPS62261DRVR
TPS62262DRVR	TPS62262DRVR
TPS62243DRVR	TPS62243DRVR
TPS62272DRVR	TPS62272DRVR
TPS62242DRVT	TPS62242DRVT
TPS62243DRVT	TPS62243DRVT
TPS62273DRVT	TPS62273DRVT
CDCLVP1204RGTT	CDCLVP1204RGTT
TPS62291DRVT	TPS62291DRVT
TPS61093DSKR	TPS61093DSKR
TPS63030DSKR	TPS63030DSKR
TPS63031DSKR	TPS63031DSKR
REG71050DRVT	REG71050DRVT
TPS61024DRCR	TPS61024DRCR
TPS61025DRCR	TPS61025DRCR
TPS63031DSKT	TPS63031DSKT
TPS61024DRCR	595-TPS61024DRCR
TPS62750DSKT	TPS62750DSKT
TPS62060DSGR	TPS62060DSGR
TPS62061DSGR	TPS62061DSGR
TPS62063DSGR	TPS62063DSGR
TPS62067DSGR	TPS62067DSGR
TPS60150DRVR	TPS60150DRVR
TPS62080DSGR	TPS62080DSGR
TPS62060DSGT	TPS62060DSGT
TPS62061DSGT	TPS62061DSGT
TPS62065DSGT	TPS62065DSGT
TPS62067DSGT	TPS62067DSGT
TPS62081DSGT	TPS62081DSGT
TPS62082DSGT	TPS62082DSGT
TLV62065DSGR	TLV62065DSGR
TLV62080DSGR	TLV62080DSGR
TLV62065DSGT	TLV62065DSGT
TPS62080ADSGT	TPS62080ADSGT
TLV62080DSGT	TLV62080DSGT
CDCLVP1204RGTR	CDCLVP1204RGTR
TPS22954DQCR	TPS22954DQCR
TPS62273DRVR	NULL
TLV62065DSGT	595-TLV62065DSGT
CDCLVP1102RGTT	CDCLVP1102RGTT
TPS62046DRCR	TPS62046DRCR
TPS62243DRVR	595-TPS62243DRVR

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20250519001.1	**PCN Date:**	May 20, 2025
Title:	Qualification of additional Assembly sites for select QFN devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 18, 2025	**Sample requests accepted until:**	July 19, 2025*

***Sample requests received after July 19, 2025 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

UQFN Build Sites	
Assembly Sites	CLARK, MLA, CARZ, ASEN, TIEMA, UTL1/UTL3, CDAT
Mount Compound	4206201
	4207123
	4207768
	4205846
	SID#435143
	SID#443497SZ
	SID#1400020112
	SID#PZ0035
	SID#PZ0109
	4224264
Mold Compound	4222198
	4223516
	SID#1800558151
Leadframe Finish	NiPdAu, Matte Sn
Bond Wire (mil)	AU (0.8, 0.96, 1.0, 1.3), CU (0.8, 0.96, 1.0, 1.3, 2.0)

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CLARK	QAB	PHL	Angeles City, Pampanga
MLA	MLA	MYS	Kuala Lumpur
CARZ	CSZ	CHN	Suzhou
ASEN	ASN	CHN	Nantong
TIEMA	CU6	MYS	Melaka
UTL1	NSE	THA	Bangkok
UTL3	UT3	THA	Bangpakong
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CDCLVP1102RGTR	TPS40040DRBT	TPS62080DSGR	TPS62272DRVT
CDCLVP1102RGTT	TPS60150DRVR	TPS62080DSGT	TPS62273DRVR
CDCLVP1204ARGTR	TPS60150DRVT	TPS62081DSGR	TPS62273DRVT
CDCLVP1204ARGTT	TPS61024DRCR	TPS62081DSGT	TPS62291DRVR
CDCLVP1204RGTR	TPS61025DRCR	TPS62082DSGR	TPS62291DRVT
CDCLVP1204RGTT	TPS61093DSKR	TPS62082DSGT	TPS62562DRVR
CDCLVP2102RGTR	TPS61093DSKT	TPS62242DRVR	TPS62562DRVT
CDCLVP2102RGTT	TPS62042DRCR	TPS62242DRVT	TPS62590DRVR
REG71050DRVR	TPS62043DRCR	TPS62243DRVR	TPS62590DRVT
REG71050DRVT	TPS62044DRCR	TPS62243DRVT	TPS62750DSKR
SN0512022DRBR	TPS62046DRCR	TPS62250DRVR	TPS62750DSKT
SN62240DRVR	TPS62060DSGR	TPS62250DRVT	TPS62751DSKR
SN62590DRVR	TPS62060DSGT	TPS62260ADRVR	TPS62751DSKT
SN62590DRVT	TPS62061DSGR	TPS62260ADRVT	TPS63030DSKR
TLV62065DSGR	TPS62061DSGT	TPS62261DRVR	TPS63030DSKT
TLV62065DSGT	TPS62063DSGR	TPS62261DRVT	TPS63031DSKR
TLV62080DSGR	TPS62063DSGT	TPS62262DRVR	TPS63031DSKT
TLV62080DSGT	TPS62065DSGR	TPS62262DRVT	TUSB1106RGTR
TPS22953DQCR	TPS62065DSGT	TPS62263DRVR	TUSB1106RTZR
TPS22953DSQR	TPS62067DSGR	TPS62263DRVT	TUSB2551ARGTR
TPS22954DQCR	TPS62067DSGT	TPS62270DRVR	
TPS22954DSQR	TPS62080ADSGR	TPS62270DRVT	
TPS40040DRBR	TPS62080ADSGT	TPS62272DRVR	

UQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CDAT TLV75733PDRV	CDAT TPS65992DADRJK	CDAT TLC6983RRF
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	2/44/0	3/66/0 (ADS5296RGC)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	Clark-AT LP5912Q1.2DRVRQ1	Clark-AT ONET4291VARGP	Clark-AT SH6966ACC0RGC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	1/22/0	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

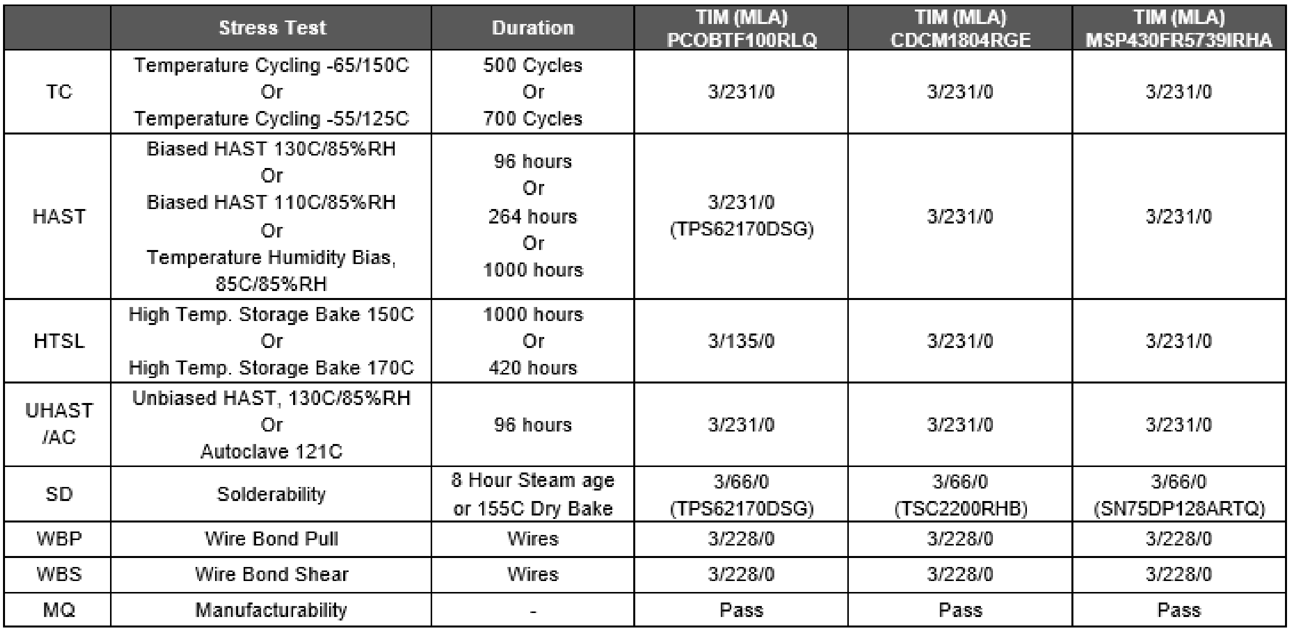
	Stress Test	Duration	ASEN CSD87502Q2	ASEN TPS65988CFRSH	ASEN TPS65126RSH
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	1/77/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0 (TIOL1XXDMW)	3/231/0	2/122/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (CSD58911Q2)	3/66/0	1/22/0 (TPS65987DDJRSH)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	CARZ TLV75733PDRV	CARZ TPD5S330RJK	CARZ UCD9211RHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0 (ADS8548SRGC)
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (DS90LV028AQDQF)	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	UTL1 TPS717XXQDRVQ1	UTL1 LM73606QRNPQ1	UTL1 SH6966ADU0RGC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	2/154/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	2/154/0	3/231/0
UHAST /AC	Unbiased HAST,130C/85%RH Or Autoclave 121C	96 hours	3/231/0	2/154/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	2/44/0	1/22/0	1/22/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	UTL3 TCAN1042DRBQ1 TPS61025DRC TCAN1051VDRBQ1	UTL3 TPS22990DML TPS62261DRV TPS62080ADSG	UTL3 CC2541F256RHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/230/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	1/22/0	3/66/0	3/66/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	Pass	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

	Stress Test	Duration	TIEMA LM26LVQISDJ1NC	TIEMA LP8548B1ASQX04	TIEMA DS125BR401Q4DK LP3971SQ-D510/NOPB
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM25066APSMGHN)	3/66/0 (LMK00334RTVTQ1)	1/22/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass



	Stress Test	Duration	TIM (MLA) PCOBTF100RLQ	TIM (MLA) CDCM1804RGE	TIM (MLA) MSP430FR5739IRHA
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0 (TPS62170DSG)	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/135/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS62170DSG)	3/66/0 (TSC2200RHB)	3/66/0 (SN75DP128ARTQ)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass	Pass

TLV75733PDRV, LP8548B1ASQX04, LM26LVQISDJ1NC, CSD87502Q2, PCOBTF100RLQ, TCAN1042DRBQ1, TCAN1042HVDRBQ1, TCAN1051VDRBQ1, TPS717XXQDRVQ1, LP5912Q1.2DRVRQ1, LP3971SQ-D510/NOPB, TPS62261DRV, and TPS61025DRC are qualified at L1-260C MSL rating.
TPS22990DML, TPD5S330RJK, ONET4291VARGP, CDCM1804RGE, TPS65992DADRJK, DS125BR401Q4DK, TPS62170DSG, LM73606QRNPQ1, TIOL1XXDMW, TPS61025DRC, and TPS62080ADSG are qualified at L2-260C MSL rating.
ADS8548SRGC, SH6966ACC0RGC, SH6966ADU0RGC, MSP430FR5739IRHA, UCD9211RHA, TPS65126RSH, TPS65988CFRSH, CC2541F256RHA, TLC6983RRF, and DP83848LFQSQE are qualified at L3-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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